

Sound Processors for Home Theater Systems

5.1ch Sound Processor

BD3811K1,BD3818KS

No.10081EAT02

Description

BD3811K1 and BD3818KS are 5.1ch sound processors, with built-in Mode Selector/Input Selector. Functions, including 6-ch Volume, Gain Amp, Bass, Treble, Mixing (BD3818KS), Dynamic Bass Boost (BD3818KS) and Bass Boost (BD3811K1) are integrated into a single chip.

Features

- 1) Independent 6 channels for Master Volume (0 to -103dB, 1dB/Step, MUTE, BD3811K1)
 - (0 to -95dB 1dB/Step, MUTE, BD3818KS)

Implementation of a resistance ladder type circuit reduces residual noise and a shock sound at switching.

2) Low current consumption design achieved by adopting the BiCMOS process

- 3) Maximum output voltage (BD3818KS): 4.3Vrms (Vcc=7V, VEE=-7V, RL=10kΩ)
- Maximum output voltage (BD3811K1): 4.2Vrms (Vcc=7V, VEE=-7V, RL=10kΩ)
- 4) Built-in Input Gain Amp useful for adjusting the output signal voltages
- 5) Built-in Operational Amplifier useful for filter construction (BD3818KS)
- 6) Built-in Dynamic Bass Boost circuit (BD3818KS)
- 7) 2-wire serial control (BD3818KS for 5V, BD3811K1 for both 3.3V and 5V)
- 8) Built-in Output Gain Amp useful for adjusting the output signal voltages (BD3811K1)
- 9) REC output terminal with a REC input/output switch useful for monitoring Equalizer Amp (BD3811K1)
- 10) Output mute controlled by either serial data or an external control terminal

Applications

AV receivers, home theater systems and mini-audio systems.

Line up matrix

Parameter	BD3811K1	BD3818KS
Input Selector	8 inputs	5 inputs
Input Gain	2Step	4 Step or 2 Step
Volume	0 to -103dB 1dB/Step	0 to -95dB 1dB/Step
Bass, Treble	±14dB 2dB/Step	±14dB 2dB/Step
Output Gain	0, 6 to 18dB 2dB/Step	Variable depending on the external resistance
Mixing	No	Yes
Bass Boost	0 to 12dB, 4dB/Step	0 to 12dB, 4dB/Step Dynamic type
Package	QFP80	SQFP80

Absolute maximum ratings (Ta=25°C)

Parameter	Symbol	Ratings	Unit	
Power Supply Voltage	VCC	7.5 ^{*1}	V	
Fower Supply voltage	VEE	-7.5	v	
Input Signal Voltage	VIN	VCC+0.3 to VEE-0.3	V	
Power Dissipation	Pd	1200 ^{*2}	mW	
Operating Temperature range	Topr	-20 to +75	°C	
Storage Temperature range	Tastg	-55 to +125	°C	

*1 Even in the specified range of Power Supply Voltage, applying voltage only to the VCC side may cause an excessive current to give a permanent damage to the IC.

When starting up power supplies, VEE and VCC should be powered on simultaneously or VEE first; then followed by VCC.

*2 Reduced by 12 mW/°C over 25°C, when installed on the standard board (size: 70x70x1.6mm).

Operating range

It must function normally at Ta=25°C.

Part No.	Parameter	Symbol		Unit				
Fait NO.	Falameter	Symbol	Min.	Тур.	Max.	Onit		
BD3811K1	Operating Supply Voltage	VCC	5	7	7.3	V		
DUSOTIKI	Operating Supply voltage	VEE	-7.3	-7	-5	v		
BD3818KS	Operating Supply Voltage	VCC	5	7	7.4	V		
00301013	Operating Supply Voltage	VEE	-7.4	-7	-5	v		

•Electrical characteristics

1)BD3811K1 (Ta=25°C, VCC=7V, VEE=-7V, f=1kHz, Vin=1Vrms, RL=10kΩ, Rg=600Ω, Input ATT=0dB, Input gain=0dB, Master volume=0dB, Output gain=0dB, Bass, Treble and bass boost=0dB, unless otherwise noted.)

	Deremeter	Currents el		Limits		Unit	Conditions
	Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
	Circuit Current	IQ		15	30	mA	No signal
	VEE		-30	-15	_	117.	i to signal
	Output Voltage Gain 1ch	Gv1	-2	0	2	dB	Measure : Pin55
	Output Voltage Gain 2ch	Gv2	-2	0	2	dB	Measure : Pin57
	Total Harmonic Distortion Ratio 1ch	THD1		0.005	0.09	%	Measure : Pin55 BW=400~30kHz
	Total Harmonic Distortion Ratio 2ch	THD2		0.005	0.09	%	Measure : Pin57 BW=400~30kHz
	Maximum Output Voltage 1ch	Vomax1	3.4	4.2		Vrms	Measure : Pin55 THD=1%
	Maximum Output Voltage 2ch	Vomax2	3.4	4.2	—	Vrms	Measure : Pin57 THD=1%
nt	Output Noise Voltage 1ch	Vno1		2.5	12	µVrms	Measure : Pin 55 Rg=0 Ω , Tone: ON BW=IHF-A
Total Output	Output Noise Voltage TCh	VIIOT	_	2.0	9.0	µVrms	Measure : Pin 55 Rg=0Ω, By Pass mode BW=IHF-A
Total	Output Noise Voltage 2ch	Vno2	_	2.5	12	µVrms	Measure : Pin 57 Rg=0 Ω , Tone: ON BW=IHF-A
	Oulput Noise Voltage 201	VIIOZ	_	2.0	9.0	µVrms	Measure : Pin 57 Rg=0Ω, By Pass mode BW=IHF-A
	Input Impedance 1ch	Rin1	28	47	70	kΩ	Measure : Pin1, 3, 5, 7, 9, 11, 77, 79
	Input Impedance 2ch	Rin2	28	47	70	kΩ	Measure : Pin2, 4, 6, 8, 10, 12, 78, 80
	Cross-talk between Channels 1ch→2ch	CTC12		-100	-70	dB	Measure : Pin57(OUT2) Rg=0Ω, BW=IHF-A Reference : Pin55(OUT1)=1Vrms
	Cross-talk between Channels $2ch \rightarrow 1ch$	CTC21		-100	-70	dB	Measure : Pin55(OUT1) Rg=0Ω, BW=IHF-A Reference : Pin57(OUT2)=1Vrms
	Cross-talk between Selectors 1ch	CTS1	_	-100	-70	dB	Measure : Pin 55 Rg=0Ω, BW=IHF-A
	Cross-talk between Selectors 2ch	CTS2	_	-100	-70	dB	Measure :Pin 57 Rg=0Ω, BW=IHF-A

	D	a		Limits			
	Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
	R Output Impedance 1ch	RoutR1		100	200	Ω	Measure : Pin 71, 73, 75
	R Output Impedance 2ch	RoutR2	—	100	200	Ω	Measure : Pin 72, 74, 76
Out	R Voltage Gain 1ch	GVR1	-2	0	2	dB	Measure : Pin 71, 73, 75 RL=47kΩ, Vin =0.4Vrms
REC C	R Voltage Gain 2ch	GVR2	-2	0	2	dB	Measure : Pin 72, 74, 76 RL=47kΩ, Vin =0.4Vrms
	R Total Harmonic Distortion Ratio 1ch	THDR1		0.005	0.09	%	Measure : Pin 71, 73, 75 RL=47kΩ, Vin =0.4Vrms BW=400~30kHz
	R Total Harmonic Distortion Ratio 2ch	THDR2		0.005	0.09	%	Measure : Pin 72, 74, 76 RL=47kΩ, Vin =0.4Vrms BW=400~30kHz
	V Output Voltage Gain 1ch	GVV1	-2	0	2	dB	Measure : Pin 36, 38
	V Output Voltage Gain 2ch	GVV2	-2	0	2	dB	Measure : Pin 35, 37
	V Total Harmonic Distortion Ratio 1ch	THDV1		0.005	0.09	%	Measure : Pin 36, 38 BW=400~30kHz
	V Total Harmonic Distortion Ratio 2ch	THDV2		0.005	0.09	%	Measure : Pin 35, 37 BW=400~30kHz
	V Output Noise Voltage 1ch	VnoV1		1.5	8	µVrms	Measure : Pin 36, 38 Rg=0Ω, BW=IHF−A
rt	V Output Noise Voltage 2ch	VnoV2		1.5	8	µVrms	Measure : Pin 35, 37 Rg=0 Ω , BW=IHF $-A$
Outpu	Volume Control Range 1ch	GVR1	-106	-103	-100	dB	Measure : Pin 36, 38, 55 Vin =3Vrms
Volume Output	Volume Control Range 2ch	GVR2	-106	-103	-100	dB	Measure : Pin 35, 37, 57 Vin =3Vrms
Ž	Volume Setting Error 1 1ch	VE11	-2	0	2	dB	Measure : Pin 36, 38, 55 0 to -53dB , Vin =3Vrms
	Volume Setting Error 1 2ch	VE12	-2	0	2	dB	Measure : Pin 35, 37, 57 0 to -53dB , Vin =3Vrms
	Volume Setting Error 2 1ch	VE21	-3	0	3	dB	Measure : Pin 36, 38, 55 -54 to -103dB , Vin =3Vrms
	Volume Setting Error 2 2ch	VE22	-3	0	3	dB	Measure : Pin 35, 37, 57 -54 to -103dB , Vin =3Vrms
	Maximum Attenuation 1ch	Vmin1	_	-118	-105	dB	Measure : Pin 36, 38, 55 Vin =3Vrms, BW=IHF-A
	Maximum Attenuation 2ch	Vmin2	_	-118	-105	dB	Measure : Pin 35, 37, 57 Vin =3Vrms, BW=IHF-A
uo	Input Attenuation Control Range 1ch	GIA1	-20	-18	-16	dB	Measure : Pin 19, 20
Input Attenuation	Input Attenuation Control Range 2ch	GIA2	-20	-18	-16	dB	Measure : Pin 17, 18
ut Att∈	Input Attenuation Setting Error 1ch	AE1	-2	0	2	dB	Measure : Pin 19, 20
lnp	Input Attenuation Setting Error 2ch	AE2	-2	0	2	dB	Measure : Pin 17, 18
	Input Gain Control Range 1ch	GIG1	4	6	8	dB	Measure : Pin 36, 38, 55 Vin =0.4Vrms
Gain	Input Gain Control Range 2ch	GIG2	4	6	8	dB	Measure : Pin 35, 37, 57 Vin =0.4Vrms
Input Gain	Input Gain Setting Error 1ch	GIE1	-2	0	2	dB	Measure : Pin 36, 38, 55 Vin =0.4Vrms
	Input Gain Setting Error 2ch	GIE2	-2	0	2	dB	Measure : Pin 35, 37, 57 Vin =0.4Vrms

	D			Limits			
	Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
	Treble Maximum Boost Gain 1ch	GTB1	12	14	16	dB	Measure : Pin 55 f=15kHz, Vin =0.4Vrms
	Treble Maximum Boost Gain 2ch	GTB2	12	14	16	dB	Measure : Pin 57 f=15kHz, Vin =0.4Vrms
	Treble Maximum Cut Gain 1ch	GTC1	-16	-14	-12	dB	Measure : Pin 55 f=15kHz, Vin =0.4Vrms
Treble	Treble Maximum Cut Gain 2ch	GTC2	-16	-14	-12	dB	Measure : Pin 57 f=15kHz, Vin =0.4Vrms
Tre	Treble Step Resolution 1ch	TR1	—	2	—	dB	Measure : Pin 55 f=15kHz, Vin =0.4Vrms
	Treble Step Resolution 2ch	TR2	_	2	_	dB	Measure : Pin 57 f=15kHz, Vin =0.4Vrms
	Treble Gain Setting Error 1ch	TE1	-2	0	2	dB	Measure : Pin 55 f=15kHz, Vin =0.4Vrms
	Treble Gain Setting Error 2ch	TE2	-2	0	2	dB	Measure : Pin 57 f=15kHz, Vin =0.4Vrms
	Bass Maximum Boost Gain 1ch	GBB1	12	14	16	dB	Measure : Pin 55 fo=100Hz, Vin=0.4Vrms
	Bass Maximum Boost Gain 2ch	GBB2	12	14	16	dB	Measure : Pin 57 fo=100Hz, Vin =0.4Vrms
	Bass Maximum Cut Gain 1ch	GBC1	-16	-14	-12	dB	Measure : Pin 55 fo=100Hz, Vin =0.4Vrms
Bass	Bass Maximum Cut Gain 2ch	GBC2	-16	-14	-12	dB	Measure : Pin 57 fo=100Hz, Vin =0.4Vrms
Ba	Bass Step Resolution 1ch	BR1		2	_	dB	Measure : Pin 55 fo=100Hz, Vin =0.4Vrms
	Bass Step Resolution 2ch	BR2		2	_	dB	Measure : Pin 57 fo=100Hz, Vin =0.4Vrms
	Bass Gain Setting Error 1ch	BE1	-2	0	2	dB	Measure : Pin 55 fo=100Hz, Vin =0.4Vrms
	Bass Gain Setting Error 2ch	BE2	-2	0	2	dB	Measure : Pin 57 fo=100Hz, Vin =0.4Vrms
	Bass Boost Maximum Gain 1ch	GBBB1	10	12	14	dB	Measure : Pin 55 fo=70Hz, Vin =0.4Vrms
	Bass Boost Maximum Gain 2ch	GBBB2	10	12	14	dB	Measure : Pin 57 fo=70Hz, Vin =0.4Vrms
Boost	Bass Boost Step Resolution 1ch	BBR1		4		dB	Measure : Pin 55 fo=70Hz, Vin =0.4Vrms
Bass I	Bass Boost Step Resolution 2ch	BBR2		4	_	dB	Measure : Pin 57 fo=70Hz, Vin =0.4Vrms
	Bass Boost Setting Error 1ch	BBE1	-2	0	2	dB	Measure : Pin 55 fo=70Hz, Vin =0.4Vrms
	Bass Boost Setting Error 2ch	BBE2	-2	0	2	dB	Measure : Pin 57 fo=70Hz, Vin =0.4Vrms
-	Output Gain Control Range 1ch	GOG1	16	18	20	dB	Measure : Pin 36, 38, 55 Vin =0.4Vrms
Output Gain	Output Gain Control Range 2ch	GOG2	16	18	20	dB	Measure : Pin 35, 37, 57 Vin =0.4Vrms
Outpu	Output Gain Setting Error 1ch	GOE1	-2	0	2	dB	Measure : Pin 36, 38, 55 Vin =0.4Vrms
	Output Gain Setting Error 2ch	GOE2	-2	0	2	dB	Measure : Pin 35, 37, 57 Vin =0.4Vrms

* Note: This IC is not designed to be radiation-resistant.

2) BD3818KS (Ta=25°C VCC=7V, VEE=-7V, f=1kHz, Vin=500mVrms, RL=10kΩ, Rg=600Ω Input gain=0dB (FL,FR), 12.6dB (C,LS,RS), 15.6dB (SUB), Master volume=0dB, Bass and Treble =0dB, Gain amp=0dB (C,LS,RS,SUB), C,LS and RS mixing=OFF, unless otherwise noted.)

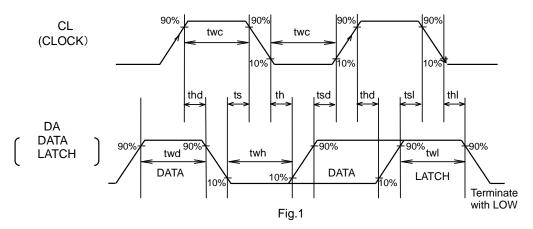
68	ain amp=0dB (C,LS,RS,SUB), C	,LS and RS	s mixing=	Limits	iess oth	ierwise no	Jieu.)
	Parameter	Symbol	Min.		Max	Unit	Conditions
			IVIII1.	Тур.	Max.		
	Circuit Current	IQ	—	28	40	mA	No signal
	Output Voltage Gain 1 Line	GV1	3	5	7	dB	Measure : Pin36,39 Vin =0.5Vrms, Line Mode
	Output Voltage Gain 1 DVD	GV1DVD	-2	0	2	dB	Measure : Pin36,39 Vin =0.5Vrms, DVD Mode
	Output Voltage Gain 1 DSP	GV1DSP	10	12	14	dB	Measure : Pin36,39 Vin =0.2Vrms, DSP Mode
	Output Voltage Gain 1 EXT	GV1EXT	-2	0	2	dB	Measure : Pin36,39 Vin =0.5Vrms, EXT Mode
	Output Voltage Gain 2	GV2	10.6	12.6	14.6	dB	Measure : Pin 23,25,27 Vin =0.2Vrms
	Output Voltage Gain 3	GV3	13.6	15.6	17.6	dB	Measure : Pin 21 Vin =0.15Vrms
	Total Harmonic Distortion Ratio 1	THD1	_	0.002	0.03	%	Measure : Pin36,39 BW=400~30kHz Vin =0.5Vrms, Line Mode
	Total Harmonic Distortion Ratio 2	THD2	_	0.003	0.03	%	Measure : Pin 23,25,27 BW=400~30kHz Vin =0.3Vrms
Output	Total Harmonic Distortion Ratio 3	THD3	_	0.003	0.03	%	Measure : Pin 21 BW=400~30kHz Vin =0.3Vrms
Total O	Maximum Output Voltage	Vomax	3.6	4.3		Vrms	Measure : Pin36,39 THD=1%
	Residual Noise Voltage 1	V _{NOR1}	_	2.7	9	µVrms	Measure : Pin36,39 Rg=0Ω,Volume= -∞ BW=IHF-A
	Residual Noise Voltage 2	V _{NOR2}	_	1.0	6	µVrms	Measure : Pin 21,23,25,27 Rg=0Ω, Volume= -∞BW=IHF-A, Output amp=0dB
	Cross-talk between Selectors	CTS	_	-90	-75	dB	Measure : Pin36,39 Rg=0Ω, BW=IHF-A
	Cross-talk between Channels Lch→Rch	CTCLR		-90	-75	dB	Measure : Pin36(OUTFR) Rg=0Ω, BW=IHF-A Reference : Pin39(OUTFL)=1Vrms
	Cross-talk between Channels $Rch \rightarrow Lch$	CTCRL	_	-90	-75	dB	Measure : Pin39(OUTFL) Rg=0Ω, BW=IHF-A Reference : Pin36(OUTFR)=1Vrms
	Cross-talk between Channels LSch \rightarrow RSch	CTCLRS		-90	-75	dB	Measure : Pin 23(OUTRS) Rg=0Ω, BW=IHF-A Reference :Pin 25(OUTLS) =1Vrms
	Cross-talk between Channels $RSch \rightarrow LSch$	CTCRLS		-90	-75	dB	Measure : Pin 25(OUTLS) Rg=0Ω, BW=IHF-A Reference :Pin 23(OUTRS) =1Vrms
	Cross-talk between Channels $Cch \rightarrow SUBch$	стссѕи		-85	-70	dB	Measure : Pin 21(OUTSUB) Rg=0Ω, BW=IHF-A Reference :Pin 27(OUTC) =1Vrms
	Cross-talk between Channels SUBch \rightarrow Cch	CTCSUC		-90	-75	dB	Measure : Pin 27(OUTC) Rg=0Ω, BW=IHF-A Reference :Pin 21(OUTSUB) =1Vrms

	Deveneter	Currente e l		Limits		l lucit	Conditions
	Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
	Volume Control Range	VOL	-97	-95	-93	dB	Measure : Pin 21,23,25,27, 36,39 VOUT=3Vrms (VOL=0dB)
Volume Output	Volume Setting Error 1	VOLE1	-1.5	0	1.5	dB	Measure : Pin 21,23,25,27,36,39 0 to -53dB, VOUT=3Vrms (at VOL=0dB)
Volume	Volume Setting Error 2	VOLE2	-2	0	2	dB	Measure : Pin 21,23,25,27,36,39 -54 to -95dB, VOUT=3Vrms (at VOL=0dB)
	Maximum Attenuation	VOLmin		-115	-105	dB	Measure : Pin 21,23,25,27,36,39 BW=IHF-A VOUT=3Vrms (at VOL=0dB)
	Treble Maximum Boost Gain	GTB	12	14	16	dB	Measure : Pin36,39, f=15kHz, Vin=0.1Vrms, Line Mode
Treble	Treble Maximum Cut Gain	GTC	-16	-14	-12	dB	Measure : Pin36,39, f=15kHz, Vin =0.1Vrms, Line Mode
Tre	Treble Step Resolution	TR	—	2	—	dB	Measure : Pin36,39, f=15kHz, Vin =0.1Vrms, Line Mode
	Treble Gain Setting Error	TE	-2	0	2	dB	Measure : Pin36,39, f=15kHz, Vin =0.1Vrms, Line Mode
	Bass Maximum Boost Gain	GBB	12	14	16	dB	Measure : Pin36,39, f=100Hz, Vin =0.1Vrms, Line Mode
Bass	Bass Maximum Cut Gain	GBC	-16	-14	-12	dB	Measure : Pin36,39, f=100Hz, Vin =0.1Vrms, Line Mode
В	Bass Step Resolution	BR	_	2	_	dB	Measure : Pin36,39, f=100Hz, Vin =0.1Vrms, Line Mode
	Bass Gain Setting Error	BE	-2	0	2	dB	Measure : Pin36,39, f=100Hz, Vin =0.1Vrms, Line Mode
	Input Gain Control Range 1	GIG1	7	9	11	dB	Measure : Pin36,39 Vin =0.1Vrms
	Input Gain Setting Error 1	GE1	-2	0	2	dB	Measure : Pin36,39 Vin =0.1Vrms
Input Gain	Input Gain Control Range 2	GIG2	13.6	15.6	17.6	dB	Measure : Pin23,25,27 Vin =0.1Vrms
ndul	Input Gain Setting Error 2	GE2	-2	0	2	dB	Measure : Pin23,25,27 Vin =0.1Vrms
	Input Gain Control Range 3	GIG3	16.6	18.6	20.6	dB	Measure : Pin21 Vin =0.1Vrms
	Input Gain Setting Error 3	GE3	-2	0	2	dB	Measure : Pin21 Vin =0.1Vrms
Gain Amp	Gain Amp Control Range	GAG	10	12	14	dB	Measure : Pin 32 Vin =0.2Vrms
Gair	Output Gain Setting Error	GAE	-2	0	2	dB	Measure : Pin 32 Vin =0.2Vrms
e Out	Line out Voltage Gain	GVLI	6	8	10	dB	Measure : Pin 59,60 Vin =0.3Vrms
Line	Line out Total Harmonic Distortion Ratio	THDLI	—	0.003	0.03	%	Measure : Pin 59,60 BW=400~30kHz, Vin =0.3Vrms

* Note: This IC is not designed to be radiation-resistant.

Timing chart

- 1. Signal Timing Conditions
 - Data is read on the rising edge of the clock.
 - Latch is read on the falling edge of the clock.
 - Latch signal must terminate with the LOW state.
 - * To avoid malfunctions, clock and data signals must terminate with the LOW state.



Parameter	Symbol		Limits		Unit
Falameter	Symbol	Min.	Тур.	Max.	Unit
Minimum Clock Width	twc	2.0	-	-	μS
Minimum Data Width	twd	2.0	-	-	μS
Minimum Latch Width	twl	2.0	-	-	μS
LOW Hold Width	twh	2.0	-	-	μS
Data Set-up Time (DATA→CLK)	tsd	1.0	-	-	μS
Data Hold Time (CLK→DATA)	thd	1.0	-	-	μS
Latch Set-up Time (CLK→LATCH)	tsl	1.0	-	-	μS
Latch Hold Time (DATA \rightarrow LATCH)	thl	1.0	-	-	μS
Latch Low Set-up Time	ts	1.0	-	-	μS
Latch Low Hold Time	th	1.0	-	-	μS

2. External Mute (Pin48) Voltage (BD3811K1)

Parameter		Limits	Unit	Conditions		
Falameter	Min.	Тур.	Max.(≤Vcc)	Offic	Conditions	
Volume Mute OFF	0 – 2.2 –		1.0	V	Vcc=5 to 7.3V	
Volume Mute ON			5.5	v	VEE=-5 to -7.3V	

3. Voltage Conditions for Control Signals

			Lin	nits					
Parameter	E	3D3811K	1	B	3D3818K	S	Unit	Conditions	
	Min.	Тур.	Max. (≤Vcc)	Min.	Тур.	Max. (≤Vcc)			
"H" Input Voltage	2.2		5.5	3.0	—	5.5	V	Vcc=5 to 7.4V	
"L" Input Voltage	0	-	1.0	0	—	1.5	V	VEE=-5 to -7.4V	

4. Basic Configuration of Control Data Formats

BD3811K1

←	Data input direction																
	MSB L													LSB			
	D16	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
Data								Data							Sele	ct Adc	lress

· Control Data Formats

• Co	Control Data Formats Solution									Sele	Select Address						
Data	D16	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
(1)	Master Volume Rch							Master Volume Lch						0	0	0	
Data	D16	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
(2)		ſ	Master	Volum	e SRcl	h				Master	· Volum	e SLch	24 2		0	0	1
Data	D16	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
(3)	Master Volume Cch							Master Volume SWch						0	1	0	
Data	D16	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
(4)	Input select REC			SW1/ N SW	REC SW3	REC SW2	Input	ATT	5.1ch Mode 1		5.1ch Mode2	Input gain	*	0	1	1	
Data	D16	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
(5)	Treble					Ва	ass		Tone	Bass	boost	Outp	ut gain	amp	1	0	0

BD3818KS

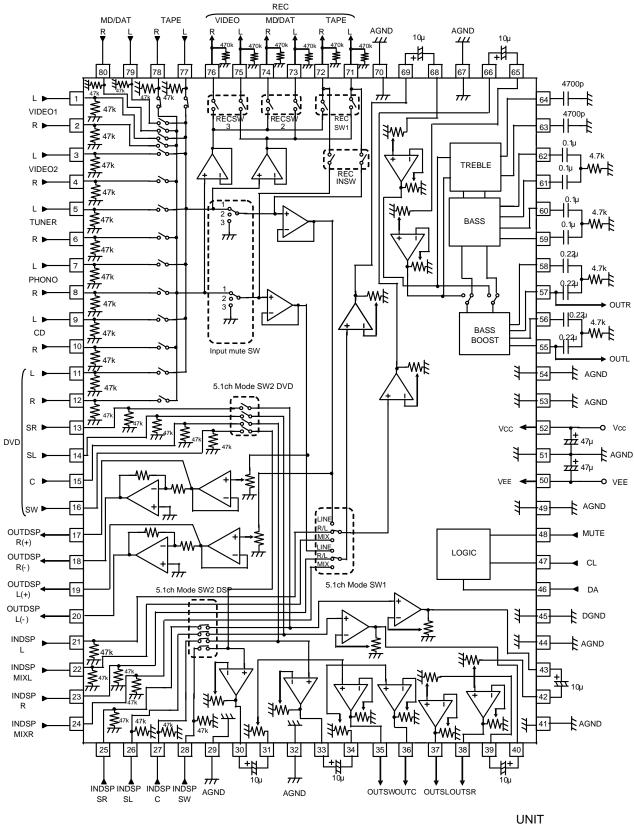
BD38	818KS																
Data input direction																	
	MSB																LSB
	D16	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
Data	Data											Sele	ct Ado	dress			

· Control Data Formats Select Address Data input direction D16 D15 D14 D13 D12 D11 D10 D9 D8 D7 D6 D5 D4 D3 D2 D1 D0 Data * * * 0 0 0 Treble Bass Tone 0 0 (1) D16 D15 D14 D13 D12 D11 D10 D9 D8 D7 D6 D5 D4 D3 D2 D1 D0 Data С SUB Input AOUT (2) Input select FLR select LRS select Line 0 1 0 0 0 select select switch select D16 D15 D14 D13 D11 D10 D12 D9 D8 D7 D6 D5 D4 D3 D2 D1 D0 Data Input Input Mix Mix Mix Gain Input gain Input (3) gain gain 1 0 0 0 0 LRS select FLŘ С amp gain C LRS SUB D16 | D15 | D14 | D13 | D12 D11 D10 D9 D8 D7 D6 D5 D4 D3 D2 D1 D0 Data (4) Master volume FLch FRch 0 0 1 Master volume D16 D15 D14 D13 D12 D11 D10 D9 D8 D7 D6 D5 D3 D2 D1 D0 D4 Data (5) LSch RSch Master volume Master volume 0 0 1 D16 D15 D14 D13 D12 D11 D10 D9 D8 D7 D6 D5 D4 D3 D2 D1 D0 Data (6) SUBch Master volume Cch Master volume 0 1 1

* Indicates 0 or 1.

Block diagram, application circuit, pin assignment

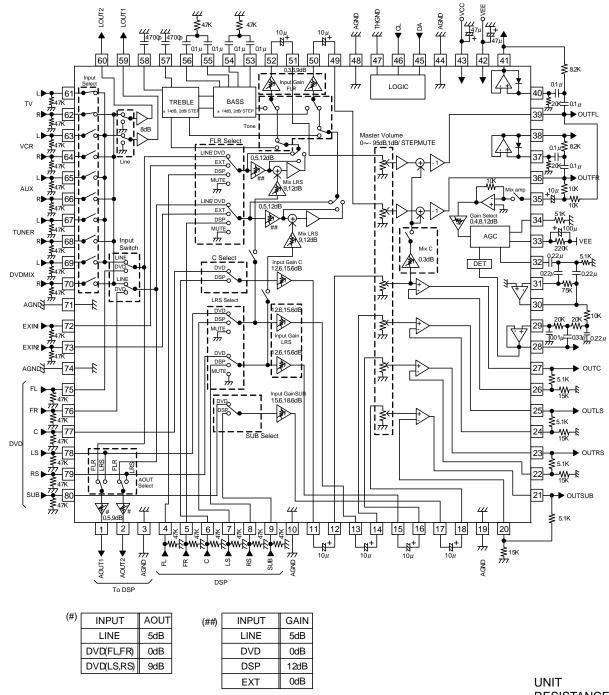
1) BD3811K1



RESISTANCE : Ω CAPACITOR : F

Fig.2

2) BD3818KS



RESISTANCE : Ω CAPACITOR : F

Fig.3

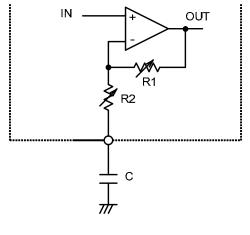
Setting constants for tone control filters

1. Treble filter

fc=1/2
$$\pi$$
 (R2)C (Hz)

 $G=20log(R1+R2+Zc)/(R2+Zc) \quad (dB)$

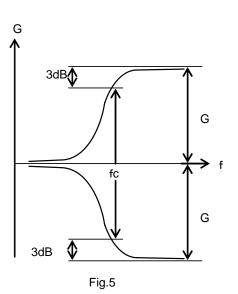
 $Zc=1/j\omega C$ (Ω)



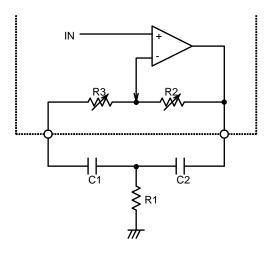


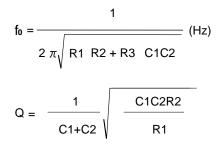
Standard values of R1, R2 (reference)						
Treble Boost Amount	Resistance (KΩ) ^{*Typ.}					
Cut Amount	R1	R2				
0dB	0	20				
±2dB	4.1	15.9				
±4dB	7.3	12.7				
±6dB	10.3	9.7				
±8dB	12.3	7.7				
±10dB	14.0	6.0				
±12dB	15.4	4.6				
±14dB	16.5	3.5				

*The actual boost cut level may deviate from the standard values in some degree.



2. Bass filter



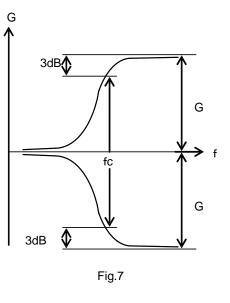


When C1=C2

$$G = 20\log \frac{\frac{R2+R3}{R1} + 2}{\frac{R3}{R1} + 2} \quad (dB)$$

Standard values of R2, R3 (reference) (R1=4.7K Ω , C1=C2=0.1 μ F)

Boost Amount	Resistance (KΩ) ^{*Typ.}			
Cut Amount	R2	R3		
0dB	0	41.0		
±2dB	10.8	30.2		
±4dB	19.3	21.7		
±6dB	26.0	15.0		
±8dB	31.2	9.8		
±10dB	35.4	5.6		
±12dB	38.4	2.6		
±14dB	41.0	0		

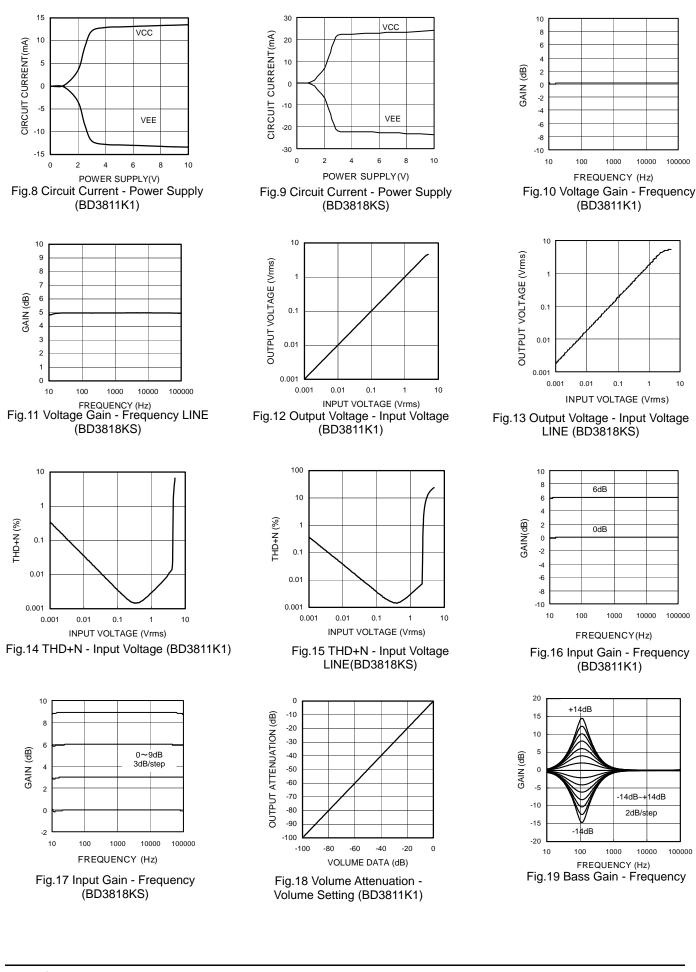


*The actual boost/cut levels may deviate from the standard values in some degree.

* Bass Filter Feature

To be able to set the f0 and Q factors of Bass characteristics to desired values, part of the Bass Filter is constructed of the external components shown in the upper-left figure.

Reference data



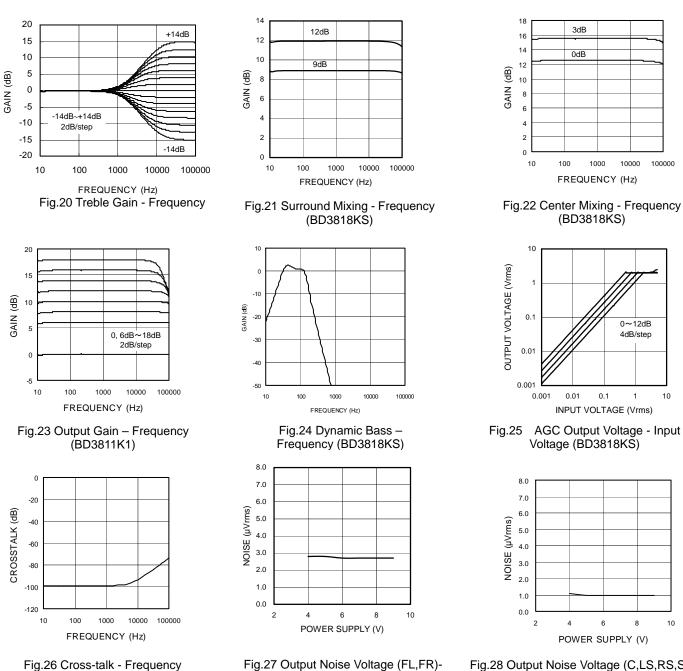


Fig.26 Cross-talk - Frequency (BD3818KS) Fig.27 Output Noise Voltage (FL,FR)-Power Supply Voltage (BD3818KS) Fig.28 Output Noise Voltage (C,LS,RS,SW)-Power Supply Voltage (BD3818KS)

Notes for use

- 1. Numbers and data in entries are representative design values and are not guaranteed values of the items.
- Although ROHM is confident that the example application circuit reflects the best possible recommendations, be sure to verify circuit characteristics for your particular application. Modification of constants for other externally connected circuits may cause variations in both static and transient characteristics for external components as well as this Rohm IC. Allow for sufficient margins when determining circuit constants.
- 3. Absolute maximum ratings

Use of the IC in excess of absolute maximum ratings, such as the applied voltage or operating temperature range (Topr), may result in IC damage. Assumptions should not be made regarding the state of the IC (short mode or open mode) when such damage is suffered. A physical safety measure, such as a fuse, should be implemented when using the IC at times where the absolute maximum ratings may be exceeded.

4. VEE potential

Make the VEE pin voltage such that it is the lowest voltage even when operating below it. Actually confirm that the voltage of each pin does not become a lower voltage than the VEE pin, including transient phenomena.

- Thermal design Perform thermal design, in which there are adequate margins, by taking into account the power dissipation (Pd) in actual states of use.
- Short circuit between terminals and erroneous mounting Pay attention to the assembly direction of the ICs. Wrong mounting direction or shorts between terminals, GND, or other components on the circuits, can damage the IC.
- Operation in strong electromagnetic field Using the ICs in a strong electromagnetic field can cause operation malfunction.

8. Serial control

For the CL and DA terminals, the patterned and other wirings should be routed not to cause interference with the analog-signal-related lines.

- 9. Power ON/OFF
 - (a) At power ON/OFF, a shock sound will be generated. Therefore, use MUTE on the set.
 - (b) When turning on power supplies, VEE and VCC should be powered on simultaneously, or VEE first followed by VCC. If the VCC side is started up first, an excessive current may flow from VCC to VEE.
- 10. Function switching

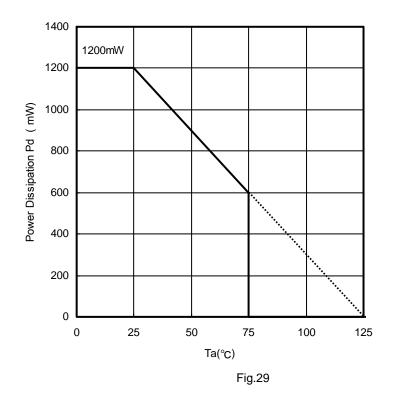
For the CL and DA terminals, the patterned and other wirings should be routed as not to cause interference with the analog-signal-related lines.

11. Ground line

The ground pin: 47pin (BD3818KS) should be connected to the ground line with as low noise as the AGND pin.

Switching noise reduction at switching volume from -3dB to -4dB (BD3811K1 only)
 In order to reduce a switching noise at the switching volume from -3dB to -4dB, the -4dB-step switch should be switched first, and then the -1dB-step switch by -1dB.

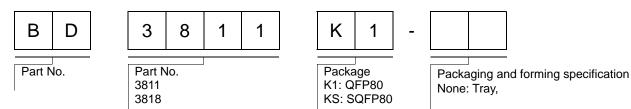
Thermal derating characteristics



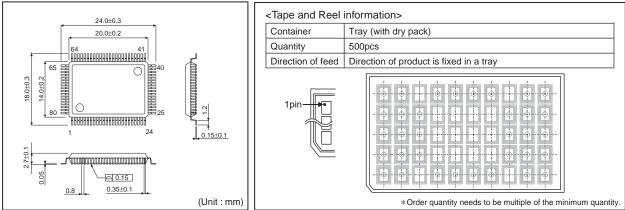
BD3811K1, BD3818KS ROHM standard board packaging time value Board size: 70 x 70 x 1.6mm Raw material: FR4 glass epoxy board (copper area 3% or below)

BD3811K1,BD3818KS

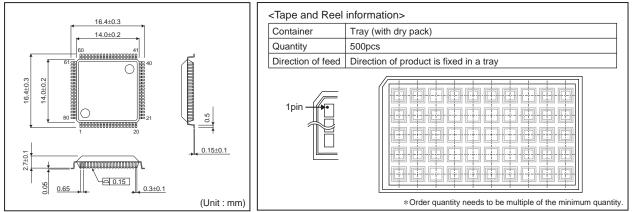
Ordering part number



QFP80



SQFP80



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JAPAN	USA	EU	CHINA		
CLASSⅢ		CLASS II b			
CLASSⅣ	CLASSⅢ	CLASSⅢ	CLASSⅢ		

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 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [C] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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